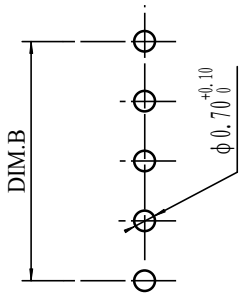
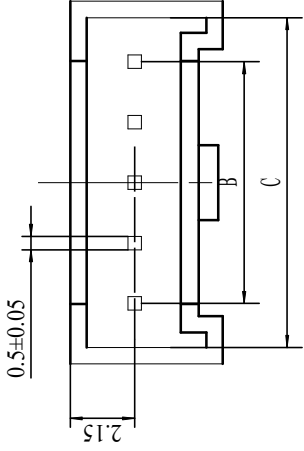
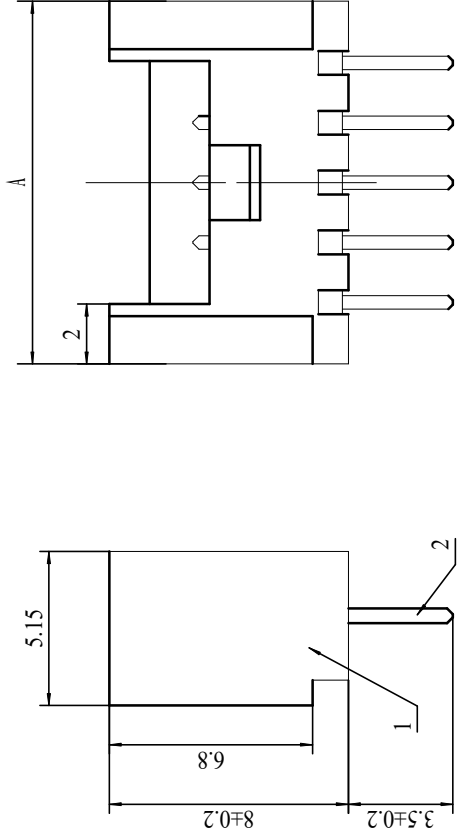


REV.	EC#	DESCRIPTION	DATE	DRAWN	CHECK	APPROVED
1.00		初版发行	2020-8-28	瞿寿坤	胡海萍	胡海萍

15P	32.0	28.0	30.9
14P	30.0	26.0	28.9
13P	28.0	24.0	26.9
12P	26.0	22.0	24.9
11P	24.0	20.0	22.9
10P	22.0	18.0	20.9
9P	20.0	16.0	18.9
8P	18.0	14.0	16.9
7P	16.0	12.0	14.9
6P	14.0	10.0	12.9
5P	12.0	8.0	10.9
4P	10.0	6.0	8.9
3P	8.0	4.0	6.9
2P	6.0	2.0	4.9
NUMBER OF PINS			DIM. C
			DIM. B
			DIM. A



PCB LAYOUT

技术要求:

- 1) 材质:见附表;
- 2) 电镀:见附表;
- 3) 塑件表面平整、光洁、无毛刺、气泡、烧焦、变形、浇口无拉伤、多料或缺料等不良现象;
- 4) 端子表面无氧化、电镀不良等现象。

适应基板厚度: 1.2mm ~ 1.6mm

温度范围: -25℃ ~ 85℃

额定电压: 250V AC/DC

额定电流: 1A

绝缘电阻: ≥ 100MΩ

耐压: 800V AC/minute

2	PIN	n PCS	材质:黄铜,电镀:镀亮锡60μm
1	Housing	1 PCS	材质:PA66, 颜色:白色
NO.	NAME	Q'TY	DESCRIPTION

DRAW :	瞿寿坤	2020-8-28	TITLE:	DRAW NAME:
DESIGN:	瞿寿坤	2020-8-28	WAPER 2.0HYA 立式 DIP	HC-HY2.0-10A-TW
CHECK:	胡海萍	2020-8-28	SERIES: 1501 SERIES	
APPROVED	胡海萍	2020-8-28	P/N:	
CUSTOMER DRAWING		REV. 1.00	SCALE	N/A
		DRAW NO.	UNIT: mm	
		SHEET:		1/1

深圳市虹成电子有限公司

GENERAL TOLERANCES		
DIM	TOL	DEC
X.	X°	+3.0°
X.X	X.X°	+2.0°
X.XX	X.XX°	+1.0°
X.XXX	X.XXX°	+0.15